

IN THE CLAIMS:

Please amend the claims as follows, all claims listed

1. (Previously Amended) A flex-print circuit (FPC) attached to at least one bonding pad on a suspension of a head gimbal assembly in a hard disk drive using anisotropic conductive adhesive, comprising:

a base film;

a conductive layer situated below the base film;

an overcoat layer comprising at least two sections situated below the conductive layer, a bottom surface of each section overlapping partially and to be pressed onto a top surface of the bonding pad; and

a conductive structure forming an electric conduit between the conductive layer and the at least one bonding pad, said anisotropic conductive adhesive being disposed at least partially surrounding the conductive structure for bonding the FPC to the at least one bonding pad.

2. (Original) The FPC of claim 1, wherein the conductive structure comprises gold.

3. (Original) The FPC of claim 1, wherein the anisotropic conductive adhesive comprises anisotropic conductive film.

4. (Original) The FPC of claim 1, wherein the conductive structure comprises a bump having a height of about 12 to 38 μm .

5. (Original) The FPC of claim 1, wherein the conductive structure comprises a gold ball.

6. (Currently Amended) The FPC of claim 1, wherein the anisotropic conductive adhesive and the conductive structure comprises a filling completely occupy ~~occupying~~ a space formed by the at least one bonding pad, the conductive layer, and the at least two sections of the overcoat layer.

7. (Canceled)

8. (Canceled)

9. (Canceled)

10. (Canceled)

11. (Canceled)

12. (Canceled)

13. (Canceled)

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15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (Canceled)

21. (Canceled)

22. (Currently Amended) The FPC of claim ~~21~~ 23, wherein the conductive bump comprises gold.

23. (Currently Amended) ~~The FPC of claim 21, further comprising~~ A flex-print circuit (FPC)
attached to a bonding pad, comprising:

a conductive layer, in said flex print circuit, bonded to the bonding pad using anisotropic
conductive adhesive;

an overcoat layer positioned below the conductive layer; and

a conductive bump lodged between the conductive layer and the bonding pad.

24. (Original) The FPC of claim 23, wherein the overcoat layer comprises two sections separated by a plating of conductive material, each of said two sections overlapping an end of a top surface of the bonding pad.

25. (Original) The FPC of claim 23, wherein the overcoat layer does not overlap the bonding pad.

26. (Currently Amended) The FPC of claim ~~21~~ 23, wherein the anisotropic conductive adhesive comprises anisotropic film.

27. (Previously Amended) A bonding device adapted for attachment to a bonding pad with an anisotropic conductive adhesive, the bonding device comprising:

a base film;

a conductive layer having a first side and a second side wherein a first side of the conductive layer is attached to the base film;

an overcoat layer attached to a first portion of a second side of the conductive layer; and

a conductive element attached to a second portion of the second side of the conductive layer wherein the conductive element is adapted to form an electrical conduit between the conductive layer and the attached bonding pad, and the overcoat layer is to press against said bonding pad.

28. (Original) A bonding device according to claim 27 wherein the overcoat layer comprises at least two sections arranged on the second side of the conductive layer such that a portion of each of the two sections overlap a portion of the bonding pad when the bonding device is attached to the bonding pad.

29. (Original) A bonding device according to claim 27 wherein the anisotropic conductive adhesive surround the conductive element when the bonding device is attached to the bonding pad.

30. (Original) A bonding device according to claim 27 wherein conductive element comprises gold.

31. (Original) A bonding device according to claim 27 wherein the anisotropic conductive adhesive comprises anisotropic conductive film.

32. (Original) A bonding device according to claim 27 wherein the conductive element comprises a bump having a height of about 12 to 38 μm .

33. (Original) A bonding device according to claim 27 wherein the conductive element comprises a gold ball.

34. (Currently Amended) A bonding device according to claim 27 wherein the the anisotropic conductive adhesive and the conductive element ~~comprises a filling that~~ completely occupies a space

formed by the bonding pad, the conductive layer, and the overcoat layer when the bonding device is attached to the bonding pad.

35. (Canceled)

36. (Canceled)

37. (Canceled)

38. (Canceled)

39. (Canceled)